

## GPI65060TO5L

N-channel 650 V 60 A GaN Power HEMT in TO263-5L package

Datasheet version: 2.5

### Features

$BV_{dss}$	$R_{dson}$	$I_{ds}$	$Q_g$
650 V	25 m $\Omega$	60 A	16 nC

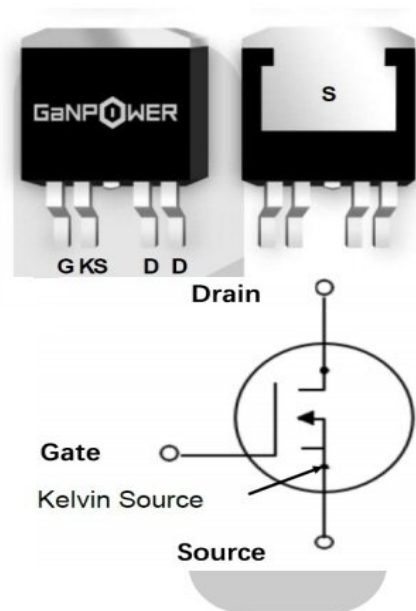
- Ultra-low  $R_{DS(on)}$
- High  $dv/dt$  capability
- Extremely low input capacitance
- Zero  $Q_{rr}$
- Outstanding switching performance
- Low Profile

### Applications

- Switching Power Applications
- Server and Telecom Power Applications
- EV OBC and DC-DC Converters

### Description

These devices are N-channel 650 V Power GaN HEMTs based on proprietary E-mode GaN on silicon technology. The resulting product has extremely low on state resistance, very low input capacitance and zero reverse recovery charge making it especially suitable for applications which require superior power density, ultra-high switching frequency and outstanding efficiency.





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230 -3410 LOUGHEED HWY  
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## Device Characteristics

Static Parameters				Test data			
	Parameters		Conditions	Min	Typical	Max	Unit
1	$V_{gs(TH)}$	Gate threshold voltage	$V_{ds}=V_{gs}$ $I_d=42mA$	0.9	1.2	2.9	V
2	$BV_{dss}$	Drain-Source breakdown voltage	$V_{gs}=0V$ $I_d<100uA$		650		V
3	$I_{dss}$	Zero gate voltage drain current, $T_c = 25^\circ C$	$V_{gs}=0V$ $V_{ds}=650V$		0.6	100	$\mu A$
4	$I_{gss}$	Gate-Source Leakage	$V_{gs} = 6V$ $V_{ds} = 0V$		0.4	6	mA
5	$R_{dson}$	Static drain-source on resistance, $T_c = 25^\circ C$	$V_{gs}=6V$ $I_d=12A$		25	30	m $\Omega$
6	$V_{sd}$	Reverse conduction voltage	$I_{sd}=1.6A$ $V_{gs}=0V$	1.5	2.9	3.0	V
7	$R_g$	Gate resistance	F=25MHz Open drain		2.18		$\Omega$
Dynamic Parameters				Test data			
	Parameters		Conditions	Min	Typical	Max	Unit
1	$C_{iss}$	Input capacitance	$V_{gs}=0V$ $V_{ds}=400V$ $f=1MHz$		420		pf
	$C_{oss}$	Output capacitance			143		pf
	$C_{rss}$	Reverse transfer capacitance			6		pf
3	$Q_g$	Gate charge	$V_{ds}=400V$ $I_d=7.5A$ $V_{gs}=6V$		16.1		nC
	$Q_{gs}$	Gate to source charge			1.1		nC
	$Q_{gd}$	Gate to drain charge			1.8		nC
2	$Q_{rr}$	Reverse recovery charge		0		nC	
Switching Performance				Test data			
	Parameters		Conditions	Min	Typical	Max	Unit
1	$t_{d(on)}$	Turn-on delay time	$V_{ds}=400V$ $I_d=2.5A$ $R_g=10\Omega$ $V_{gs}=6V$		28		ns
2	$t_r$	Rise time			16		ns
3	$t_{d(off)}$	Turn-off delay time			40		ns
4	$t_f$	Fall time			90		ns



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## Absolute Max. Ratings

	Symbols	Parameters	Value	Unit
1	$V_{DS-max}$	Breakdown voltage transient @ $T_{case}=25^{\circ}C$	800	V
2	$V_{GS-max}$	Gate to source max. transient voltage @ $T_{case}=25^{\circ}C$	-12 to +7.5	V
3	$I_{ds-max}$	Drain to source DC current @ $T_{case}=25^{\circ}C$	60	A
4	$I_{ds-max}$	Drain to source DC current @ $T_{case}=100^{\circ}C$	50	A
5	$dv/dt_{-max}$	Drain to source voltage slew rate	200	V/ns
6	$T_J-max$	Max junction temperature	150	$^{\circ}C$
7	$T_S-storage$	Storage temperature	-55 to 150	$^{\circ}C$

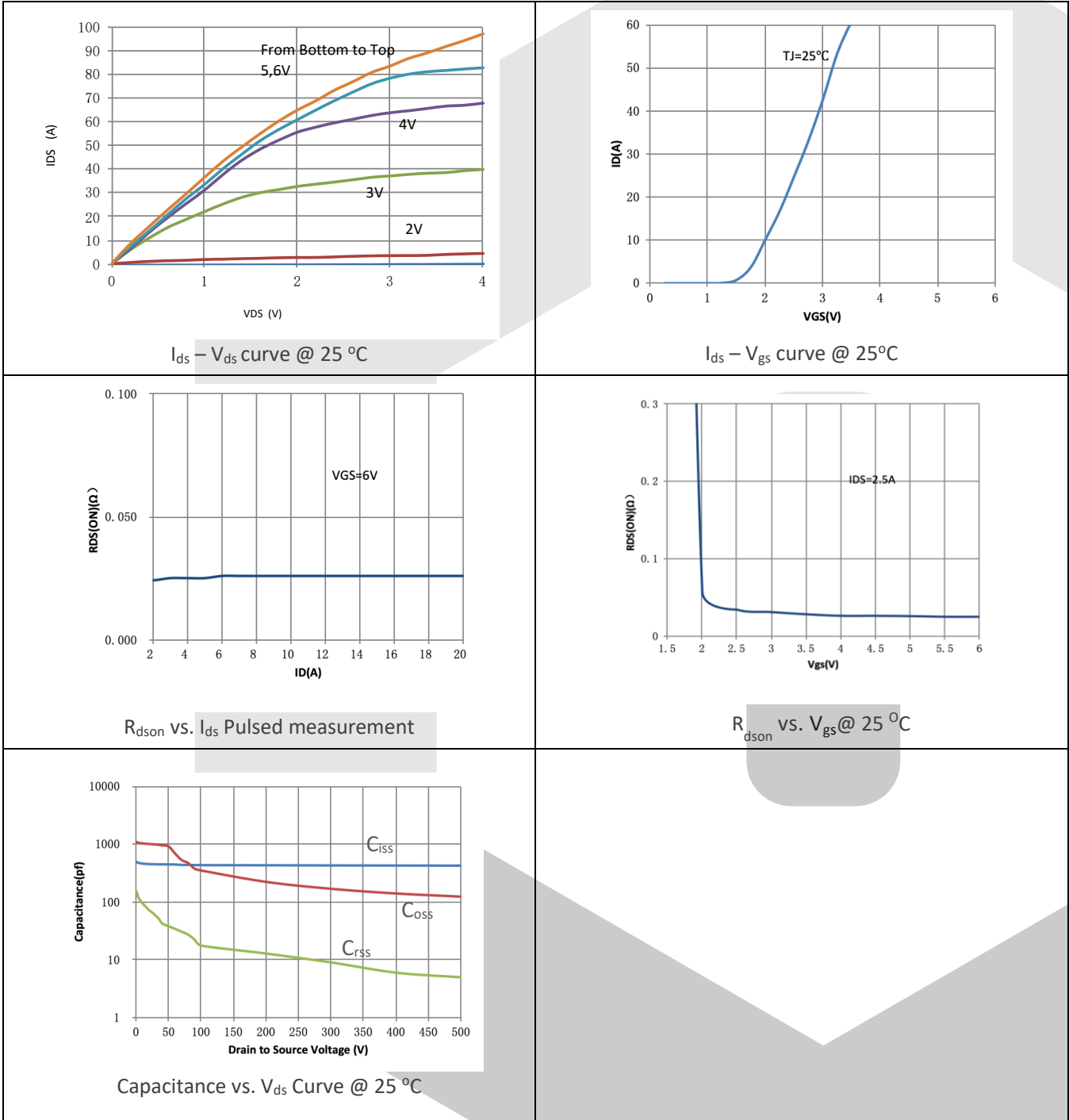
## Thermal and Soldering Characteristics (Typical)

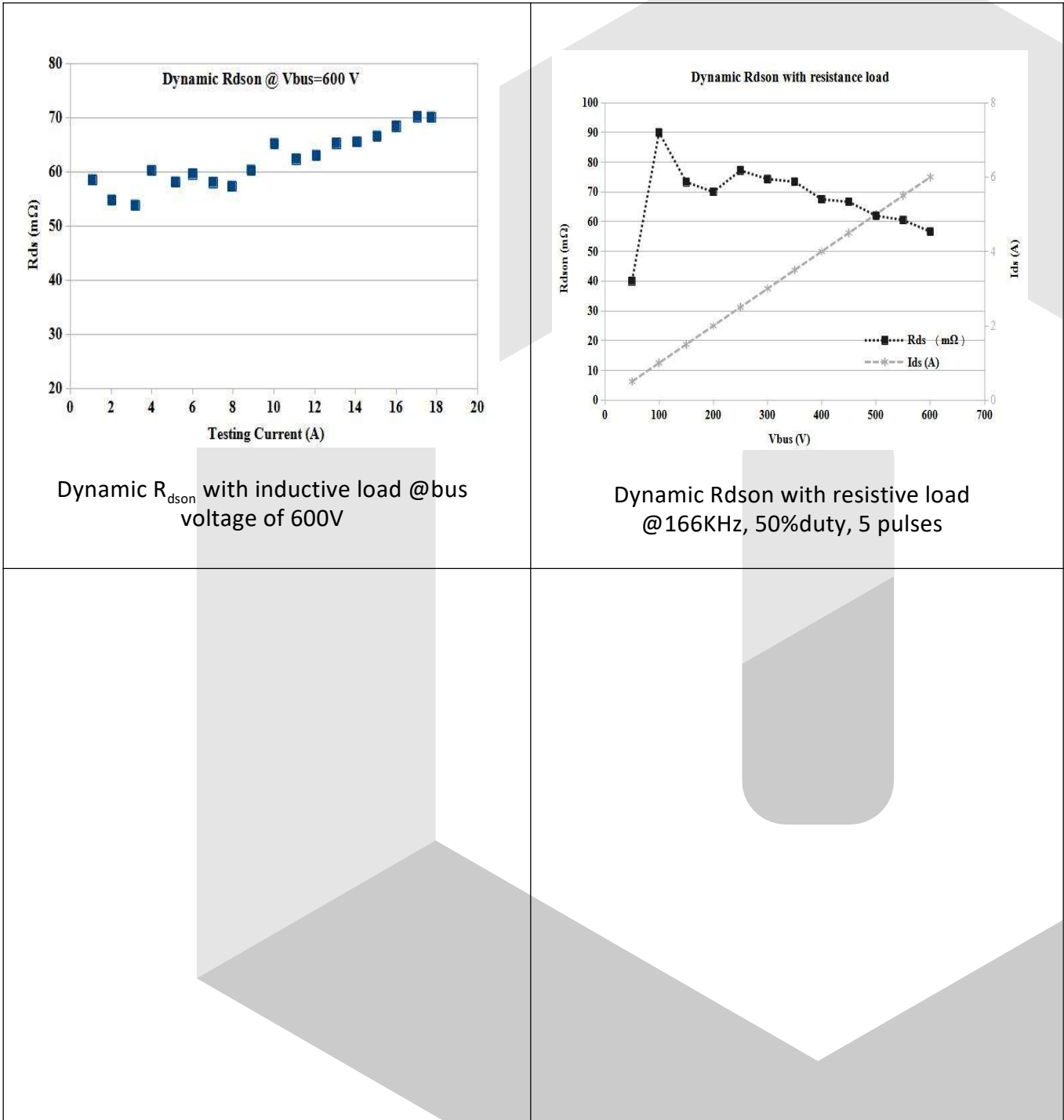
	Symbols	Parameters	Value	Unit
1	$R_{thJC}$	Thermal resistance (junction to case)	0.6	$^{\circ}C/W$
2	$R_{thJA}$	Thermal resistance (junction to ambient)	62	$^{\circ}C/W$
2	$T_{solder}$	Reflow soldering temperature	260	$^{\circ}C$

## Ordering

Order Code	Package Type	Packaging Method	Qty
GPI65060TO5L	TO263-5L		

## Electrical Performance

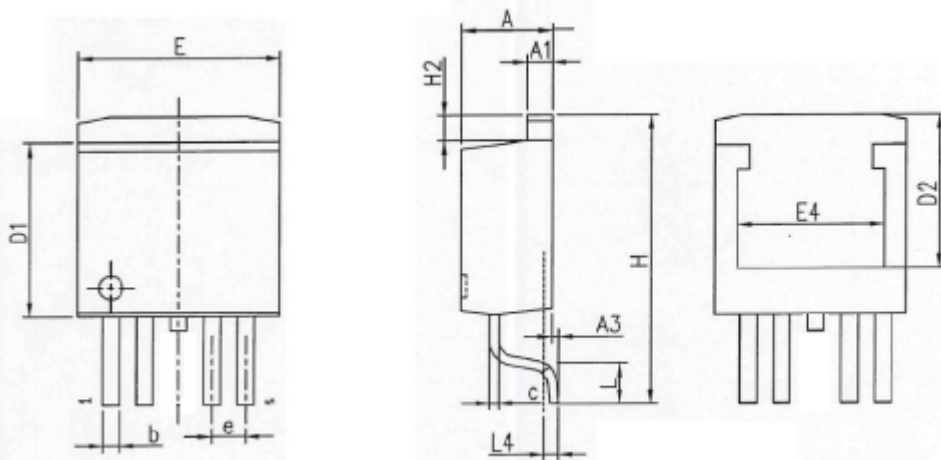
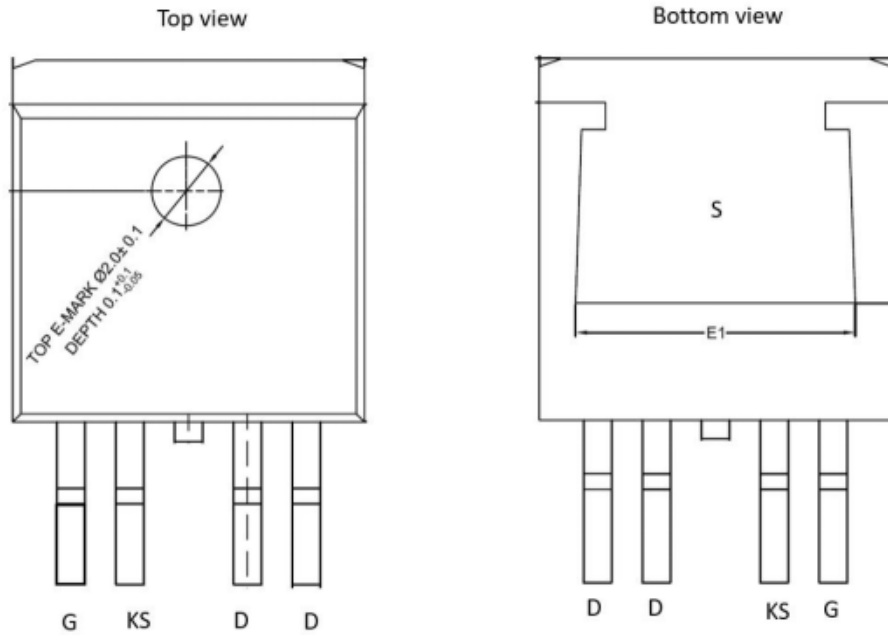




Dynamic R<sub>ds(on)</sub> with inductive load @ bus voltage of 600V

Dynamic R<sub>ds(on)</sub> with resistive load @166KHz, 50%duty, 5 pulses

## Package Information



COMMON DIMENSIONS

SYMBOL	UM		
	MIN	NOM	MAX
A	4.37	4.57	4.77
A1	1.17	1.27	1.42
A3	0	-	0.25
b	0.71	-	0.97
c	0.33	-	0.76
D1	8.38	8.70	9.00
D2	6.00	-	-
E	9.90	10.16	10.39
E4	7.30	-	-
e	1.70BSC		
H	-	-	14.35
H2	-	-	1.27
L	-	198	-
L4	-	0.76	-



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## Further Information

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**Data Source**– Data here are based on recent tests but all parameters may not be up to date. Actual final test data from packaging production are available for selected customers upon request.